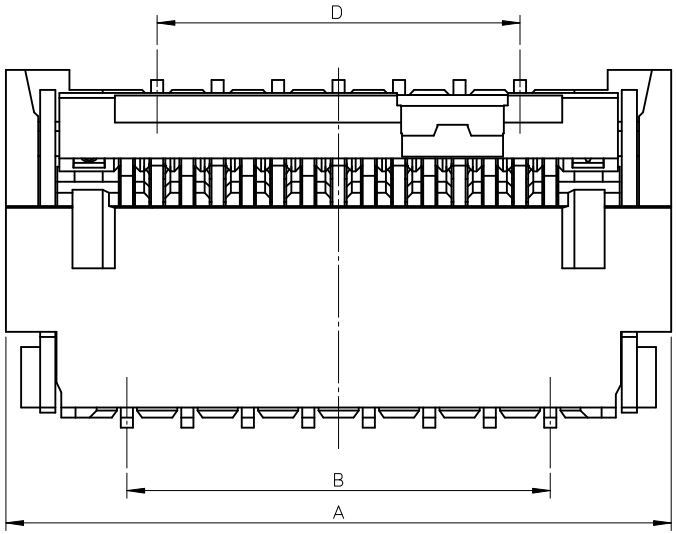
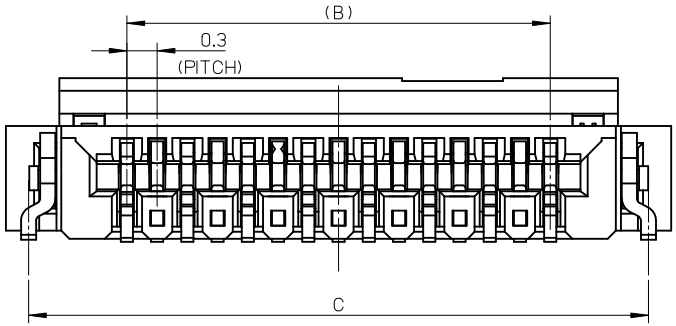
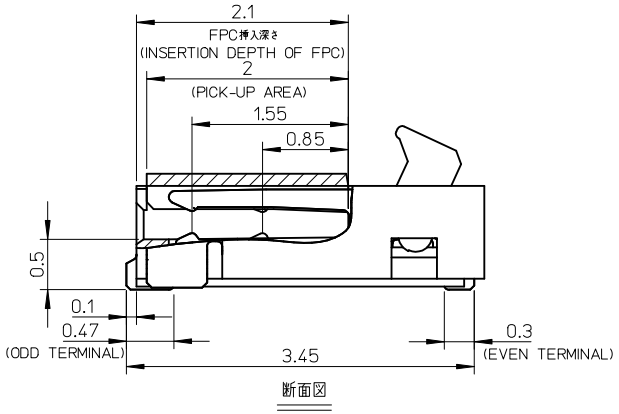
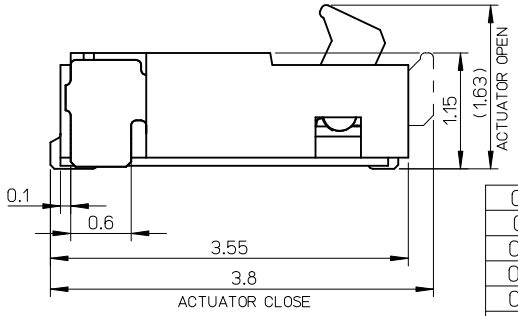






断面図



注記 NOTES:

1.材質 MATERIAL
ハウジング：LCP(液晶ポリマー)、白色、ガラス充填、UL94V-0
HOUSING:LIQUID CRYSTAL POLYMER,WHITE(NATURAL)
GLASS FILLED,UL94V-0
アクチュエータ：ポリアミド樹脂
黒色、ガラス充填、UL94V-HB
ACTUATOR: POLYAMIDE
BLACK GLASS FILLED,UL94V-HB
ターミナル：銅合金(t=0.12)
TERMINAL:COPPER ALLOY(t=0.12)
金具：燐青銅(t=0.15)
NAIL:PHOSPHOR BRONZE(t=0.15)

2.めっき仕様 PLATING
ターミナル TERMINAL
接点部：金めっき 0.1μm以上
CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM
半田付け部：金めっき
SOLDER TAIL AREA: GOLD
下地めっき:ニッケル 1.0μm以上
UNDER PLATING:NICKEL 1.0 MICROMETER MINIMUM
金具 NAIL
錫めっき 1.0μm以上
TIN PLATING 1.0 MICROMETER MINIMUM
下地めっき:ニッケル 1.0μm以上
UNDER PLATING:NICKEL 1.0 MICROMETER MINIMUM

3.平坦度は、0.1ミリ以下とする。
TAILS COPLANARITY TO BE 0.1 MAXIMUM.

4.製品の取り扱いについては、コネクタ取り扱い説明書(AS-502598-001)を参照願います。
PLEASE REFER TO INSTRUCTION MANUAL(AS-502598-001) FOR 0.3 FPC CONNECOR BACK FLIP.

5.ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

重さ (g) WEIGHT(g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS
0.125	14.4	16.95	15	17.4	502598-5191	51
0.112	12.6	15.15	13.2	15.6	502598-4591	45
0.098	10.8	13.35	11.4	13.8	502598-3991	39
0.085	9	11.55	9.6	12	502598-3391	33
0.077	7.8	10.35	8.4	10.8	502598-2991	29
0.072	7.2	9.75	7.8	10.2	502598-2791	27
0.068	6.6	9.15	7.2	9.6	502598-2591	25
0.063	6	8.55	6.6	9	502598-2391	23

CONNECTOR SERIES NO. 502598-**11

REVISED
EC NO: J2012-0121
DRWN:YUHASEGAWA 2011/07/25
CH'KD:KTAKAHASHI 2011/07/25
APPR:KMORIKAWA 2011/07/28
DESCRIPTION
REV
C

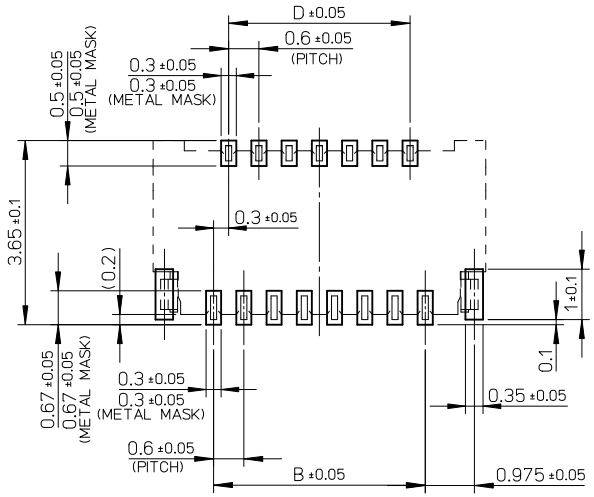
GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±1 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	20:1
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY / DATE	HONO 2009/07/21
CHECKED BY / DATE	HSHIMOYAMA 2009/07/21
APPROVED BY / DATE	KMORIKAWA 2009/07/21
MATERIAL NO.	SEE TABLE
TITLE	0.3 FPC CONN. BACK FLIP HOUSING ASSY
	MOLEX INCORPORATED
DOCUMENT NO.	SD-502598-001
SHEET NO.	1 OF 2
SIZE	A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

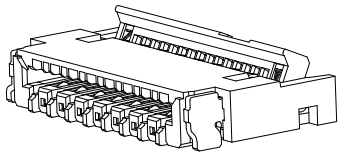


推奨基板寸法

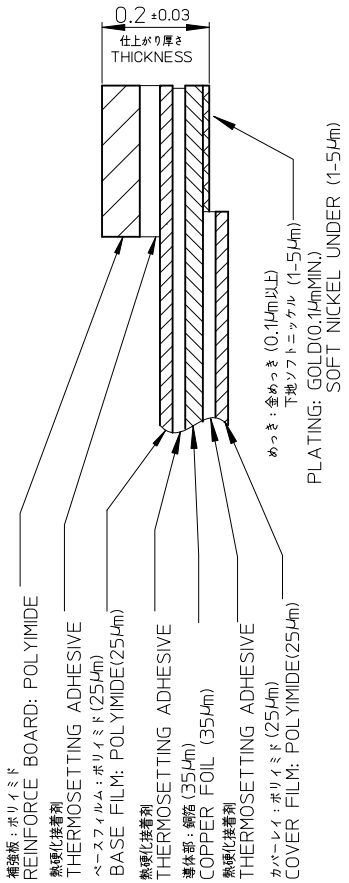
RECOMMENDED P.W.B. PATTERN LAYOUT

推奨メタルマスク厚：t=0.1mm

RECOMMENDED METAL MASK THICKNESS:t=0.1mm

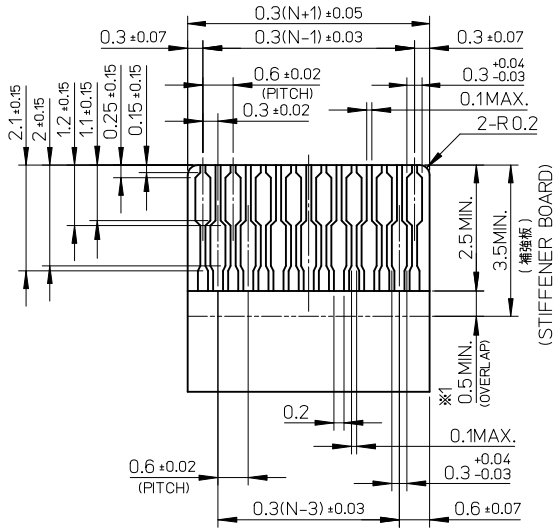


ISO VIEW （参考）



FPC構成推奨仕様

STRUCTURE OF FPC



適合する金めっきFPC推奨寸法

APPLICABLE FPC OF GOLD PATING
RECOMMENDED DIMENSION

（仕上がり厚さ：0.2±0.03）

(THICKNESS:0.2±0.03)

N：極数

N:CIRCUITS

FPCについて：

抜き方向は、導体側から補強板側を推奨致します。

補強フィルム材質は、ポリイミドを推奨致します。

接着剤は熱硬化接着剤を推奨致します。

尚、接着剤の接点部への付着は導通不良の原因になりますので、

染み出しが無い様、お願い致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.

RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING AGENT

PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

※1 補強板の長さが図面通りに確保できない場合は、カバーレイと補強板のオーバーラップ寸法を0.5mm以上としてください。

WHEN STIFFNER BOARD DIMENSION CAN NOT SECURE AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF COVER FILM AND STIFFNER BOARD AS 0.5mm MINIMUM.

REVISED
EC NO: J2012-0121
DRWN:YUHASEGAWA 2011/07/25
CH'KD:KTAKAHASHI 2011/07/25
APPR:KMORIKAWA 2011/07/28
DESCRIPTION
REV C

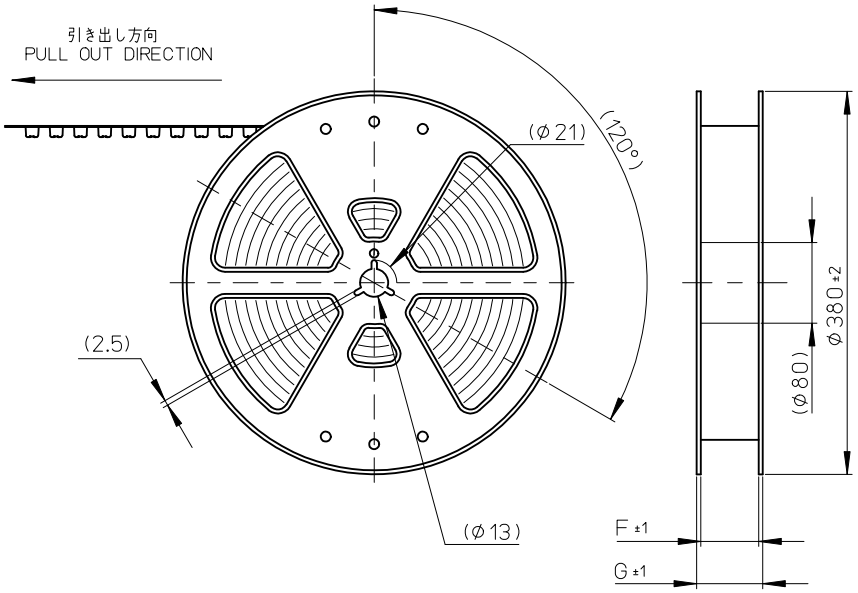
GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±1 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	-/-
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY / DATE	HONO 2009/07/21
CHECKED BY / DATE	HSHIMOYAMA 2009/07/21
APPROVED BY / DATE	KMORIKAWA 2009/07/21
MATERIAL NO.	SEE TABLE
TITLE	0.3 FPC CONN. BACK FLIP HOUSING ASSY
	MOLEX INCORPORATED
DOCUMENT NO.	SD-502598-001
SHEET NO.	2 OF 2
SIZE	A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

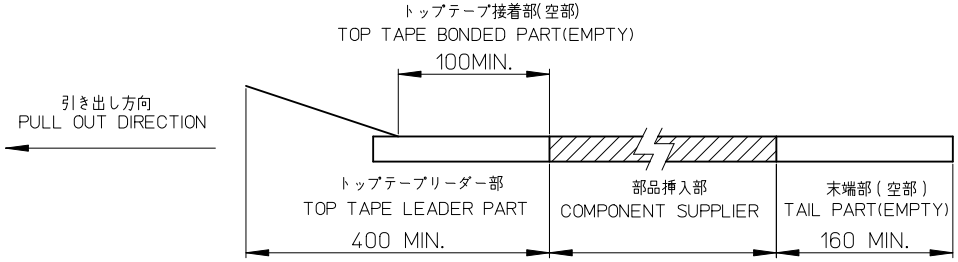


注記)
NOTES

1.製品番号502598-**11の詳細寸法は、製品単体図面を参照下さい.
IN THE PACAKGE PART NUMBER 502598-**11 DETAIL DIMENSIONS, SEE SALES DRAWING FOR CONNECTOR.

2.梱包数量:3000個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL

3.リードテープ長さ
LEAD TAPE LENGTH



4.カバーテープの剥離強度については、IEC60286-3に準拠
COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.

5.材料
MATERIAL
キャリアテープ:ポリスチレン(PS)
CARRIER TAPE:POLYSTYRENE(PS)
トップテープ:ポリエチレンテレフタラート(PET)、他
TOP TAPE :POLYETHYLENE TELEPHTHALATE(PET), OTHERS
リール:ポリスチレン(PS)
REEL:POLYSTYLENE(PS)

6.ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

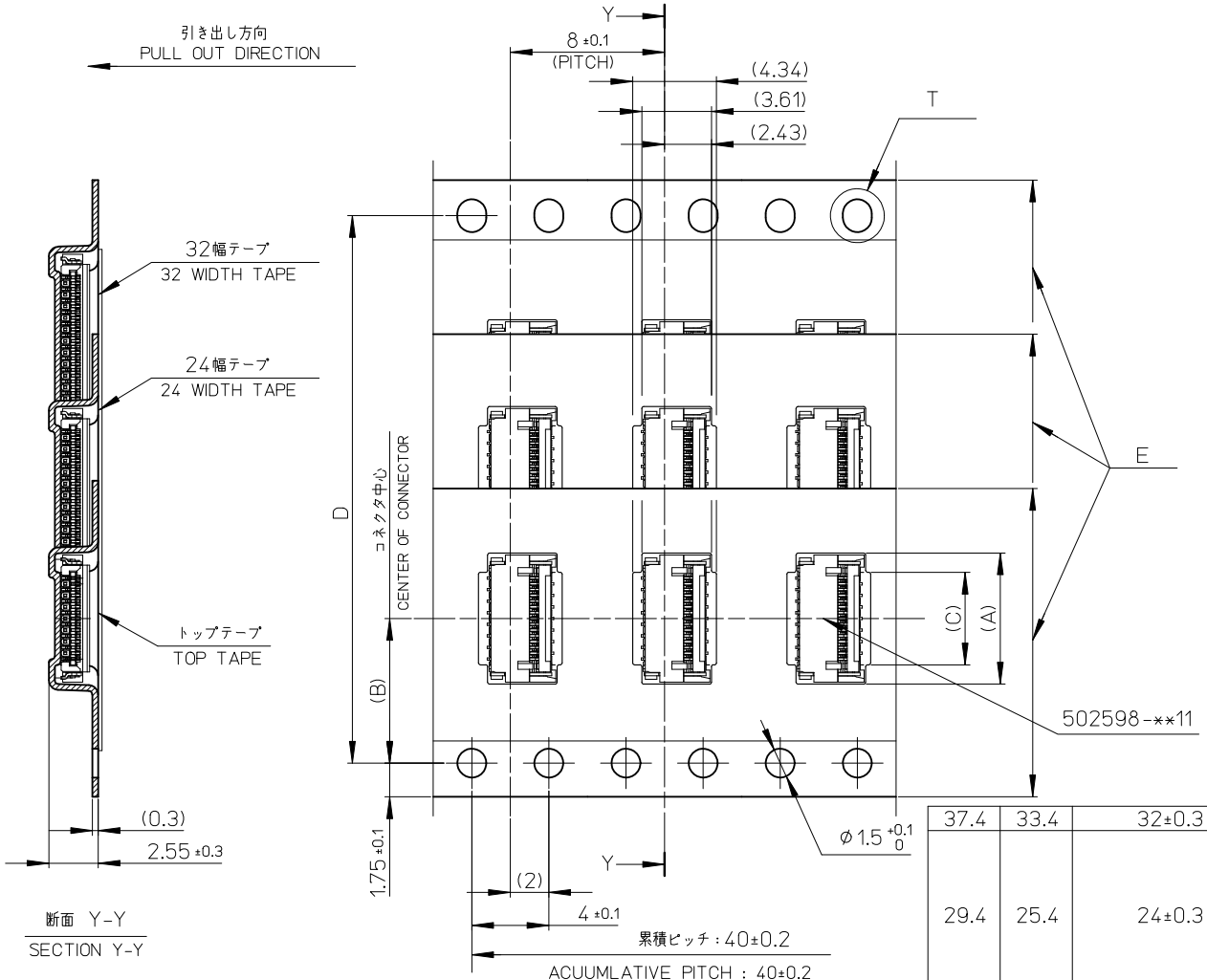
REVISED
EC NO: J2011-0028 2010/07/06
DRWN:HONO01 2009/07/21
CH'KD:HSHIMOYAMA 2009/07/21
APPR:KMORIKAWA 2010/07/08
DESCRIPTION
REV B

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	± ---
10 OVER 30 UNDER	± ---
30 OVER	± ---
ANGULAR ±1 °	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY	SCALE: ---	DESIGN UNITS: METRIC	THIRD ANGLE PROJECTION
DRAWN BY: HONO DATE: 2009/07/21	TITLE: 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (502598-**11 SERIES)		
CHECKED BY: HSHIMOYAMA DATE: 2009/07/21			
APPROVED BY: KMORIKAWA DATE: 2009/07/21	molex MOLEX INCORPORATED		
MATERIAL NO.: SEE TABLE	DOCUMENT NO.: SD-502598-002	SHEET NO.: 1 OF 2	
SIZE: A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



G	F	E キャリアテープ幅 EMBOSSED TAPE WIDTH	D	C	B	A	製品番号 MATERIAL NO.	極数 CIRCUITS
37.4	33.4	32±0.3	28.4	15.7	14.2	17.6	502598-5191	51
				13.9		15.8	502598-4591	45
				12.1		14	502598-3991	39
				10.3		12.2	502598-3391	33
29.4	25.4	24±0.3	〃	9.1	11.5	11	502598-2991	29
				8.5		10.4	502598-2791	27
				7.9		9.8	502598-2591	25
				7.3		9.2	502598-2391	23

REVISED
EC NO: J2011-0028 2010/07/06
DRWN:HONO01 2009/07/21
CH'KD:HSHIMOYAMA 2009/07/21
APPR:KMORIKAWA 2010/07/08
DESCRIPTION
REV B

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	± ---
10 OVER 30 UNDER	± ---
30 OVER	± ---
ANGULAR ±1 °	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

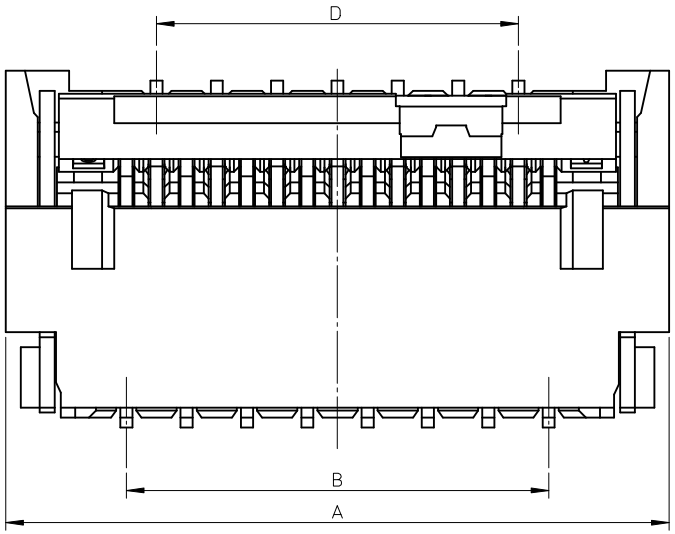
DRAWN BY: HONO DATE: 2009/07/21
CHECKED BY: HSHIMOYAMA DATE: 2009/07/21
APPROVED BY: KMORIKAWA DATE: 2009/07/21
MATERIAL NO.: SEE TABLE

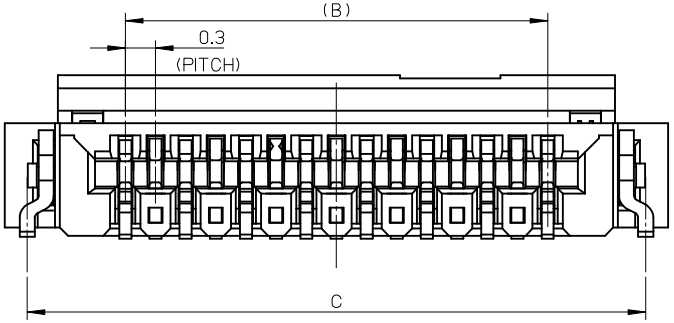
TITLE: 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (502598-**11 SERIES)

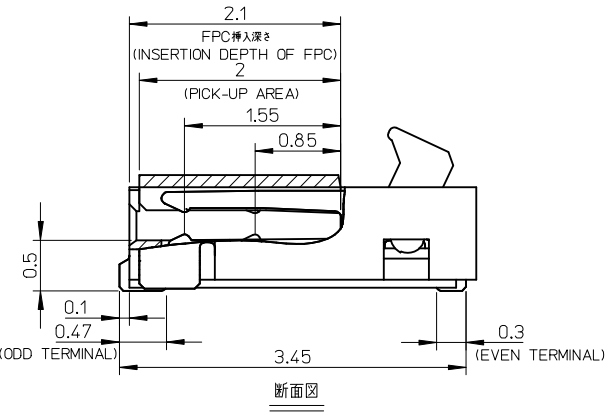
MOLEX INCORPORATED

DOCUMENT NO.: SD-502598-002
SHEET NO.: 2 OF 2
SIZE: A3

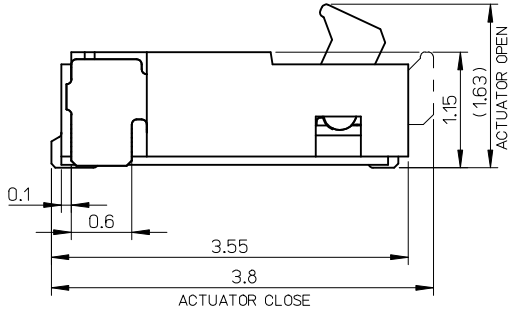
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION







断面図



注記 NOTES:

1.材質 MATERIAL
- ハウジング：LCP(液晶ポリマー)、白色、ガラス充填、UL94V-0
- HOUSING:LIQUID CRYSTAL POLYMER,WHITE(NATURAL) GLASS FILLED,UL94V-0
- アクチュエータ：ポリアミド樹脂 黒色、ガラス充填、UL94HB
- ACTUATOR: POLYAMIDE BLACK GLASS FILLED,UL94HB
- ターミナル：燐青銅(t=0.12)
- TERMINAL:PHOSPHOR BRONZE(t=0.12)
- 金具：燐青銅(t=0.15)
- NAIL:PHOSPHOR BRONZE(t=0.15)

2.めっき仕様 PLATING

ターミナル TERMINAL
- 接点部：金めっき 0.1μm以上
- CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM
- 半田付け部：金めっき
- SOLDER TAIL AREA: GOLD
- 下地めっき:ニッケル 1.0μm以上
- UNDER PLATING:NICKEL 1.0 MICROMETER MINIMUM

金具 NAIL
- 錫めっき 1.0μm以上
- TIN PLATING 1.0 MICROMETER MINIMUM
- 下地めっき:ニッケル 1.0μm以上
- UNDER PLATING:NICKEL 1.0 MICROMETER MINIMUM

3.平坦度は、0.1ミリ以下とする.
TAILS COPLANARITY TO BE 0.1 MAXIMUM.

4.ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

5.本製品は502598-**91の端子材料変更品である.
THIS PRODUCT IS CHANGE OF TERMINAL MATERIAL FOR 502598-**91.

重さ (g) WEIGHT(g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS
0.125	14.4	16.95	15	17.4	502598-5193	51
0.112	12.6	15.15	13.2	15.6	502598-4593	45
0.105	11.4	13.95	12.0	14.4	502598-4193	41
0.098	10.8	13.35	11.4	13.8	502598-3993	39
0.085	9	11.55	9.6	12	502598-3393	33
0.077	7.8	10.35	8.4	10.8	502598-2993	29
0.072	7.2	9.75	7.8	10.2	502598-2793	27
0.068	6.6	9.15	7.2	9.6	502598-2593	25
0.063	6	8.55	6.6	9	502598-2393	23
0.048	4.2	6.75	4.8	7.2	502598-1793	17
0.043	3.6	6.15	4.2	6.6	502598-1593	15

CONNECTOR SERIES NO. 502598-**21

REVISED
EC NO: J2014-0146 2013/07/25
DRWN:KNAGUMO 2013/08/30
CH'KD:KTAKAHASHI 2013/08/28
APPR:YNOGAWA
DESCRIPTION
B
REV

GENERAL TOLERANCES (UNLESS SPECIFIED)

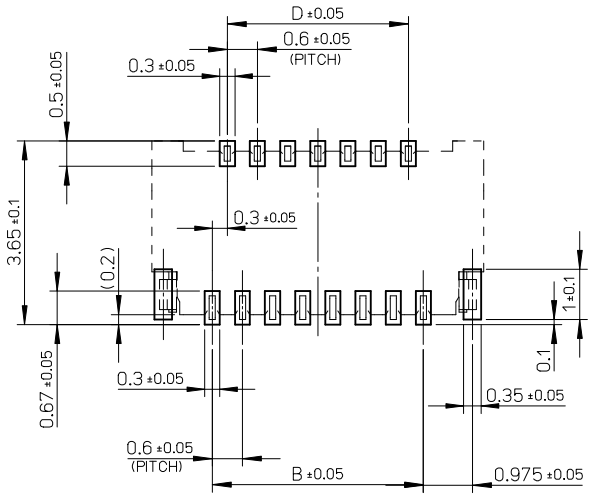
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±1 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	---
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY / DATE	KMIYAHARA 2012/07/18
CHECKED BY / DATE	KTAKAHASHI 2012/07/18
APPROVED BY / DATE	KMORIKAWA 2012/08/01
MATERIAL NO.	SEE TABLE
TITLE	0.3 FPC CONN. BACK FLIP HOUSING ASSY
DOCUMENT NO.	SD-502598-003
SHEET NO.	1 OF 2
SIZE	A3

molex

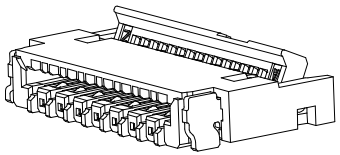
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



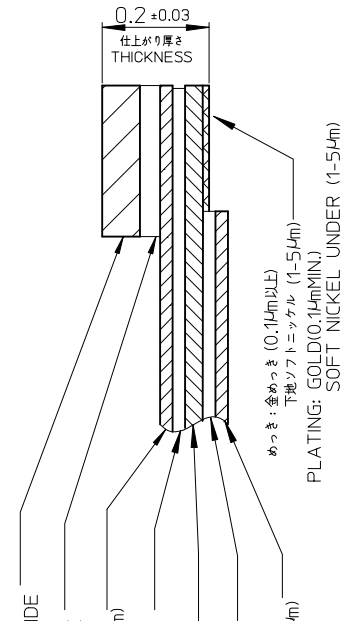
推奨基板寸法

RECOMMENDED P.W.B. PATTERN LAYOUT

マスク厚：100μm
マスク開口率：100%
SCREEN THICKNESS：100μm
SCREEN OPEN RATIO：100%

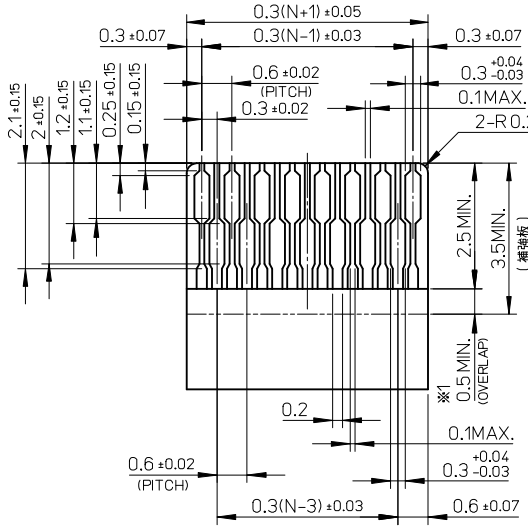


ISO VIEW （参考）



FPC構成推奨仕様

STRUCTURE OF FPC



N：極数
N:CIRCUITS

適合する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PATING
RECOMMENDED DIMENSION

(仕上がり厚さ：0.2±0.03)
(THICKNESS:0.2±0.03)

FPCについて：
抜き方向は、導体側から補強板側を推奨致します。
補強フィルム材質は、ポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、
染み出しが無い様、お願い致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

REVISED
EC NO: J2014-0146
DRWN:KNAGUMO 2013/07/25
CHKD:KTAKAHASHI 2013/08/30
APPR:YNOGAWA 2013/08/28
DESCRIPTION
B
REV

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±1 °	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	---
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY / DATE	KMIYAHARA 2012/07/18
CHECKED BY / DATE	KTAKAHASHI 2012/07/18
APPROVED BY / DATE	KMORIKAWA 2012/08/01
MATERIAL NO.	SEE TABLE
TITLE	0.3 FPC CONN. BACK FLIP HOUSING ASSY
DOCUMENT NO.	SD-502598-003
SHEET NO.	2 OF 2
SIZE	A3

molex

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Общество с ограниченной ответственностью «МосЧип» ИНН 7719860671 / КПП 771901001
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Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

http://moschip.ru/get-element

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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